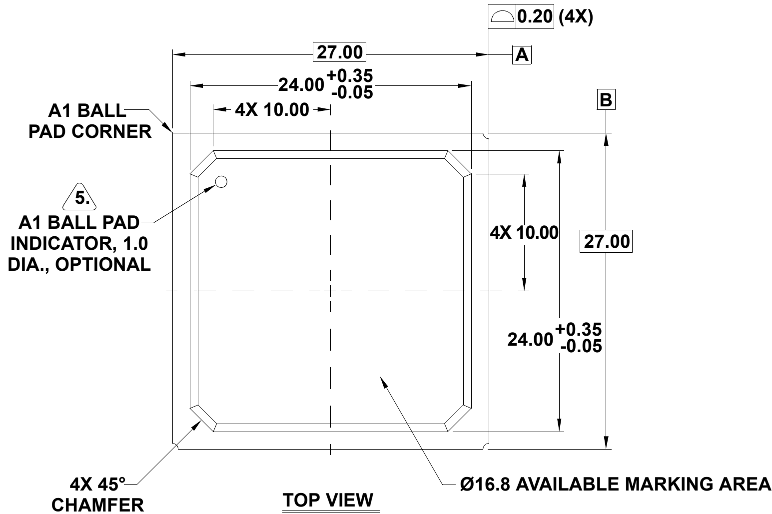
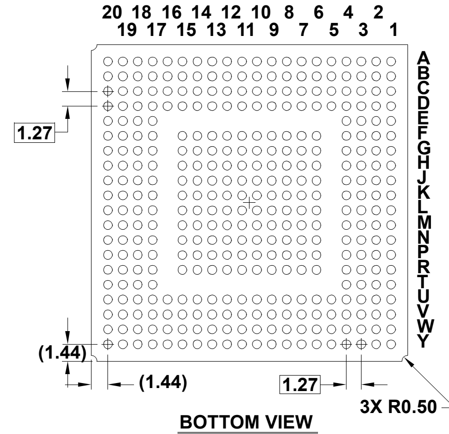
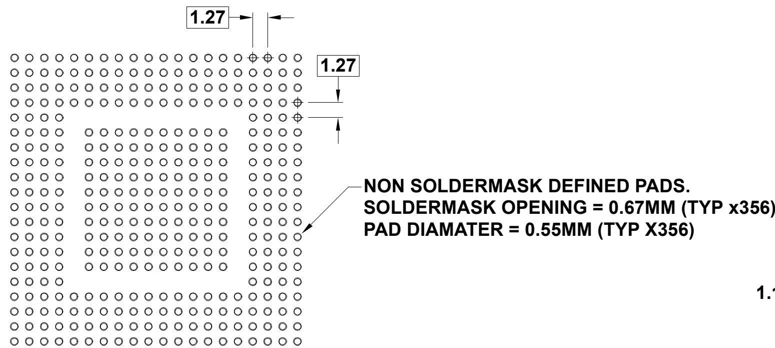
Package Outline Drawing

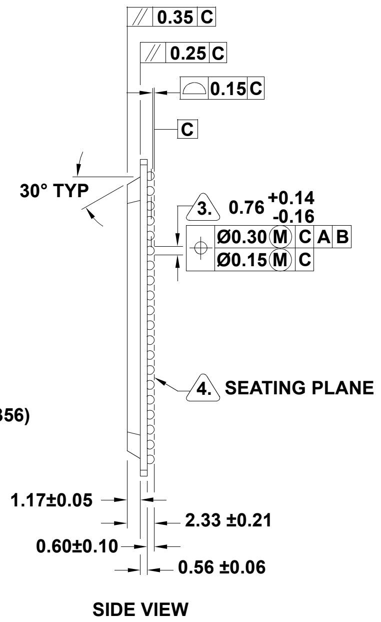
V356.27x27B

356 BALL PLASTIC BALL GRID ARRAY PACKAGE (PBGA)
Rev 2, 10/10









NOTES:

1. All dimensions and tolerances conform to ASME Y14.5M-1994.
2. Dimensions are in millimeters.
3. Dimension is measured at the maximum solder ball diameter, parallel to primary datum C.
4. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
5. A1 ball pad corner I.D. for plate mold: To be marked by ink. Auto mold: Dimple to be formed by mold cap.
6. Reference specifications: This drawing conforms to JEDEC registered outline MS-034/A variation BAL-2.